

Exhibit C

ASSIGNMENT AND AGREEMENT

For value received, we, Bret K. Street; James M. Derderian; and Jeremy E. Minnich, hereby sell, assign and transfer to Micron Technology, Inc., a corporation of the State of Delaware, having an office at 8000 S. Federal Way, Boise, Idaho 83706-9632, U.S.A., and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to an invention entitled A DIE PACKAGE HAVING AN ADHESIVE FLOW RESTRICTION AREA, described in an application for Letters Patent of the United States, executed by us of even date herewith, and all the rights and privileges in said application and under any and all Letters Patent that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Micron Technology, Inc. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Micron Technology, Inc. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Micron Technology, Inc. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Micron Technology, Inc. in the United States and in all countries foreign to the United States, or to such nominees as Micron Technology, Inc. may designate.

We agree that, when requested, we shall, without charge to Micron Technology, Inc. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

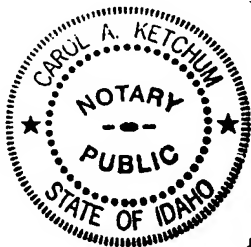
Bret K Street
Bret K. Street

Date: 12/16/03

United States of America)
State of Idaho) ss.:
County of Ada)

On this 16th day of December, 2003, before me personally came Bret K. Street, to me known to be the individual described in and who executed the foregoing instrument, and acknowledged execution of the same.

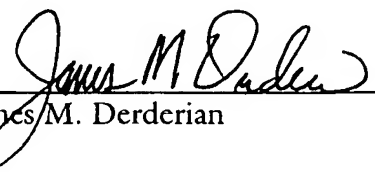
Carol A Ketchum
Notary Public



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ASSIGNMENT AND AGREEMENT

Signature Page for Second Inventor

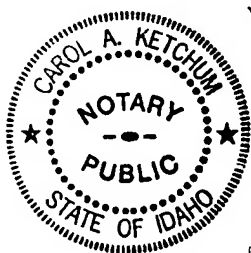

James M. Derderian

Date: 12/16/2003

United States of America)
State of Idaho) ss.:
County of Ada)

On this 16th day of December, 2003, before me
personally came James M. Derderian, to me known to be the individual
described in and who executed the foregoing instrument, and acknowledged execution
of the same.

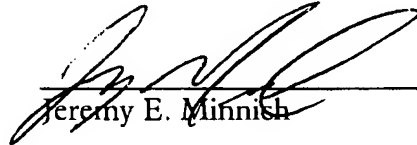

Notary Public



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ASSIGNMENT AND AGREEMENT

Signature Page for Third Inventor

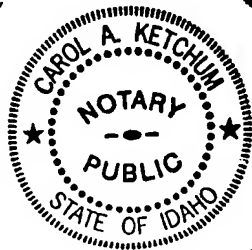


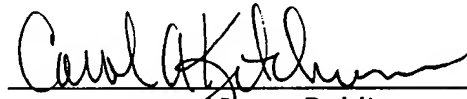
Jeremy E. Minnich

Date: 12/16/03

United States of America)
State of Idaho) ss.:
County of Blaine)

On this 16th day of December, 2003, before me
personally came Jeremy E. Minnich, to me known to be the individual
described in and who executed the foregoing instrument, and acknowledged execution
of the same.





Notary Public